What is claimed is:

~~1. A method of manufacture of an integrated circuit packaging system comprising:~~

~~providing a first substrate;~~

~~attaching vertical interconnects along a periphery of the first substrate;~~

~~mounting an integrated circuit over the first substrate, the integrated circuit surrounded by the vertical interconnects; and~~

~~mounting a second substrate directly on the vertical interconnects and the integrated circuit.~~

~~2.~~ 6.The method as claimed in claim 1 wherein mounting the integrated circuit includes mounting the integrated circuit over the first substrate, the integrated circuit having an integrated circuit inactive side coplanar with a top extent of each of the vertical interconnects.

~~3.~~ 7.The method as claimed in claim 1 wherein attaching the vertical interconnects includes attaching the vertical interconnects perpendicular to the first substrate.

~~4.~~ 8.The method as claimed in claim 1 wherein attaching the vertical interconnects includes attaching the vertical interconnects directly on the first substrate, the vertical interconnects having vertical heights approximately equal to each other.

~~5.~~ 9.The method as claimed in claim 1 further comprising forming an encapsulation partially covering the vertical interconnects.

~~6.~~1. A method of manufacture of an integrated circuit packaging system comprising:

providing a first substrate;

attaching vertical interconnects along a periphery of the first substrate;

mounting an integrated circuit over the first substrate, the integrated circuit surrounded by the vertical interconnects; and

mounting a second substrate directly on the vertical interconnects and an integrated circuit inactive side of the integrated circuit.

~~7.~~2. The method as claimed in claim ~~6~~1 wherein mounting the integrated circuit

includes mounting the integrated circuit over the first substrate, the integrated circuit surrounded by a peripheral array of the vertical interconnects.

~~8.~~3. The method as claimed in claim ~~6~~1 further comprising mounting a second integrated circuit over the second substrate.

~~9.~~4. The method as claimed in claim ~~6~~1 wherein mounting the second substrate includes mounting ~~a stack package having~~ the second substrate directly on the vertical interconnects and the integrated circuit inactive side, the second substrate further including a stack package.

~~10.~~5. The method as claimed in claim ~~6~~1 wherein mounting the second substrate includes mounting the second substrate directly on the vertical interconnects and the integrated circuit inactive side, the second substrate having a horizontal length less than a horizontal length of the first substrate.

~~11. An integrated circuit packaging system comprising:~~

~~a first substrate;~~

~~vertical interconnects along a periphery of the first substrate;~~

~~an integrated circuit over the first substrate, the integrated circuit surrounded by the vertical interconnects; and~~

~~a second substrate directly on the vertical interconnects and the integrated circuit.~~

~~12.~~ 15.The system as claimed in claim 1~~1~~0 wherein the ~~integrated circuit includes an~~ integrated circuit inactive side is coplanar with a top extent of each of the vertical interconnects.

~~13.~~ 16.The system as claimed in claim 1~~1~~0 wherein the vertical interconnects are perpendicular to the first substrate.

~~14.~~ 17.The system as claimed in claim 1~~1~~0 wherein the vertical interconnects include vertical heights approximately equal to each other.

~~15.~~ 18.The system as claimed in claim 1~~1~~0 further comprising an encapsulation partially covering the vertical interconnects.

~~16.~~ 10.~~The system as claimed in claim 11~~ An integrated circuit packaging system comprising:

a first substrate;

vertical interconnects along a periphery of the first substrate;

an integrated circuit over the first substrate, the integrated circuit surrounded by the vertical interconnects; and

a second substrate directly on the vertical interconnects and the integrated circuit,

wherein the second substrate is directly on an integrated circuit inactive side of the integrated circuit.

~~17.~~ 11.The system as claimed in claim 1~~6~~0 wherein the integrated circuit is surrounded by a peripheral array of the vertical interconnects.

~~18.~~ 12.The system as claimed in claim 1~~6~~0 further comprising a second integrated circuit over the second substrate.

~~19.~~ 13.The system as claimed in claim 1~~6~~0 wherein the second substrate further includes a

stack package~~ having the second substrate directly on the vertical interconnects and the integrated circuit inactive side~~.

~~20.~~ 14.The system as claimed in claim 1~~0~~6 wherein the second substrate includes a horizontal length less than a horizontal length of the first substrate.